

# FP1008R1 and FP1008R2

## High frequency, high current power inductors



### Applications

- Servers
  - Multi-phase and Vcore regulators
  - Voltage Regulator Modules (VRMs)
- Desktop VRMs and EVRDs
- Data networking and storage systems
- Graphics cards and battery power systems
- Point-of-Load modules
- DCR Sensing circuits

### Environmental data

- Storage temperature range (Component): -40°C to +125 °C
- Operating temperature range: -40°C to +125°C (ambient + self-temperature rise)
- Solder reflow temperature: J-STD-020D compliant

### Product description

- High current carrying capacity
- Low core loss
- Controlled DCR for sensing circuits
- Inductance range from 120nH to 300nH
- Current range from 38 to 112 amps
- 10.8 x 8.5 mm footprint surface mount package in an 8.0 mm height
- Ferrite core material
- Halogen free, lead free, RoHS compliant

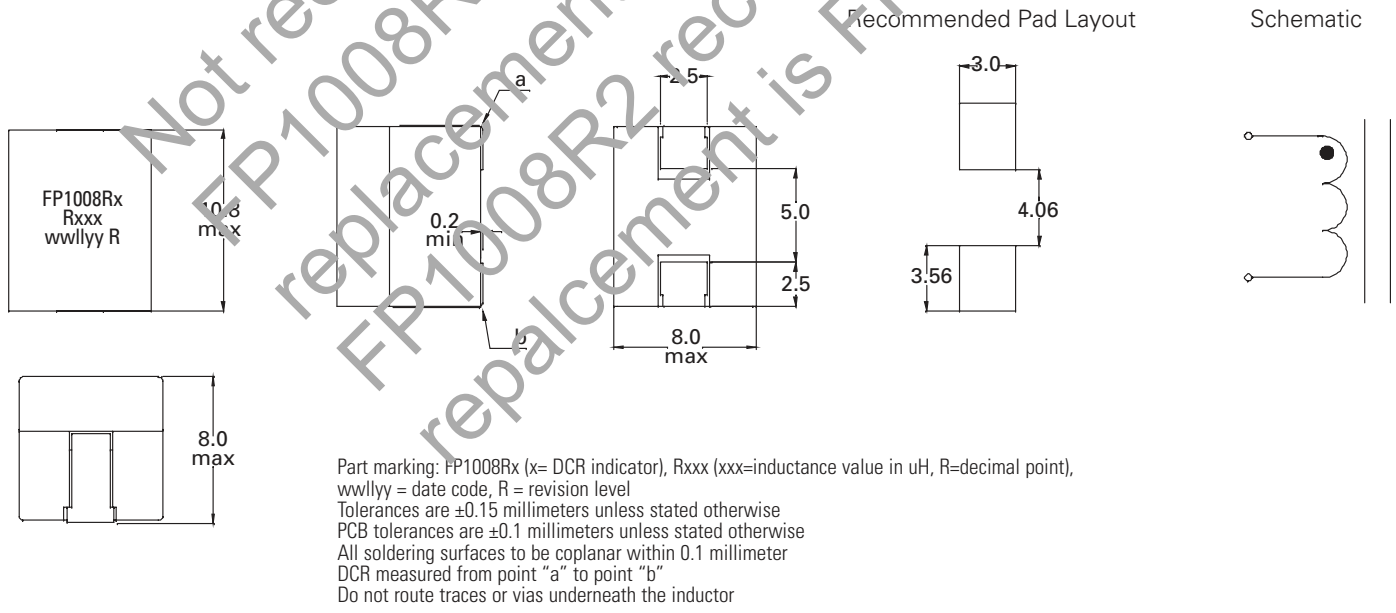


Product specifications

Part Number <sup>9</sup>	OCL <sup>1</sup> (nH)±10%	FLL <sup>2</sup> (nH) minimum	I <sub>rms</sub> <sup>3</sup> (amps)	I <sub>sat</sub> 1 <sup>4</sup> (amps)	I <sub>sat</sub> 2 <sup>5</sup> (amps)	I <sub>sat</sub> 3 <sup>6</sup> (amps)	DCR (mΩ) ±5% @ 20°C	K-factor <sup>7</sup>
<b>R1 version</b>								
FP1008R1-R120-R	120	86	79	112	92	84	0.17	342
FP1008R1-R150-R	150	108	79	90	72	67	0.17	342
FP1008R1-R180-R	180	130	79	74	60	54	0.17	342
FP1008R1-R220-R	220	158	79	56	44	42	0.17	342
FP1008R1-R270-R	270	194	79	44	34	32	0.17	342
FP1008R1-R300-R	300	216	79	38	30	28	0.17	342
<b>R2 version</b>								
FP1008R2-R120-R	120	86	74	112	92	84	0.18	342
FP1008R2-R150-R	150	108	74	90	72	67	0.18	342
FP1008R2-R180-R	180	130	74	74	60	54	0.18	342
FP1008R2-R220-R	220	158	74	56	44	42	0.18	342
FP1008R2-R270-R	270	194	74	44	34	32	0.18	342
FP1008R2-R300-R	300	216	74	38	30	28	0.18	342

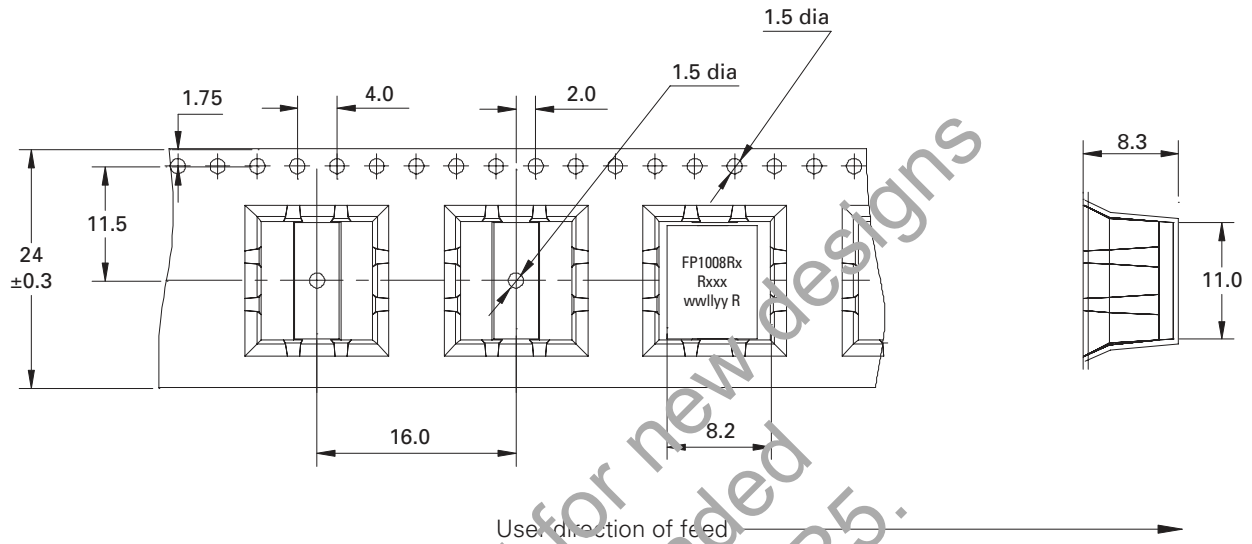
- Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, 0.0Adc, +25°C
- Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1V<sub>rms</sub>, I<sub>sat</sub>1, +25°C
- I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat-generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- I<sub>sat</sub>1: Peak current for approximately 20% rolloff @ +25°C
- I<sub>sat</sub>2: Peak current for approximately 20% rolloff @ +100°C
- I<sub>sat</sub>3: Peak current for approximately 20% rolloff @ +125°C
- K-factor: Used to determine B<sub>avg</sub> for core loss (see graph).  
B<sub>avg</sub> = K \* L \* ΔI \* 10<sup>-3</sup> / 2π (Gauss), K: (K factor from table),  
L (Inductance in nH), ΔI (Peak-to-peak ripple current in Amps).
- Part Number Definition: FP1008Rx-Rxxx-R  
FP1008R - Product code and size  
x = DCR indicator  
Rxx = Inductance value in μH, R = decimal point  
R suffix = RoHS compliant

Dimensions (mm)

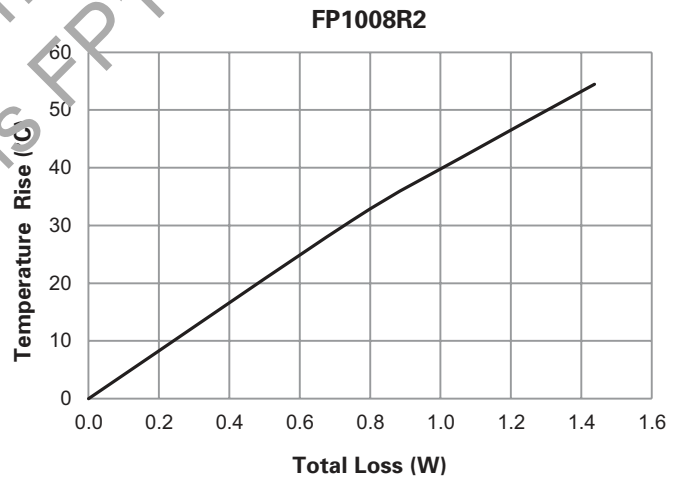
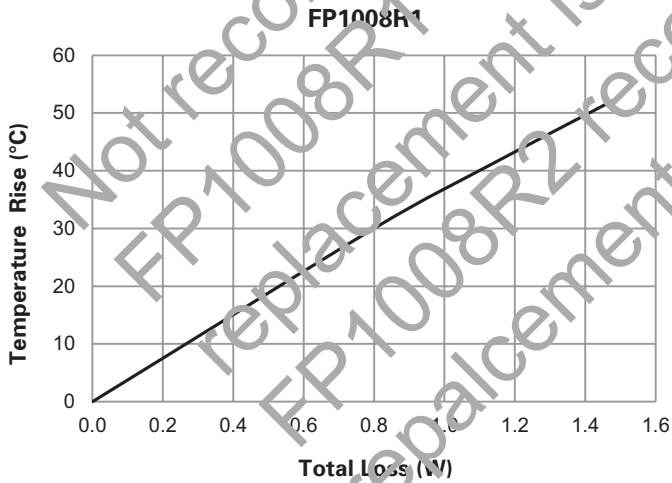


**Packaging information (mm)**

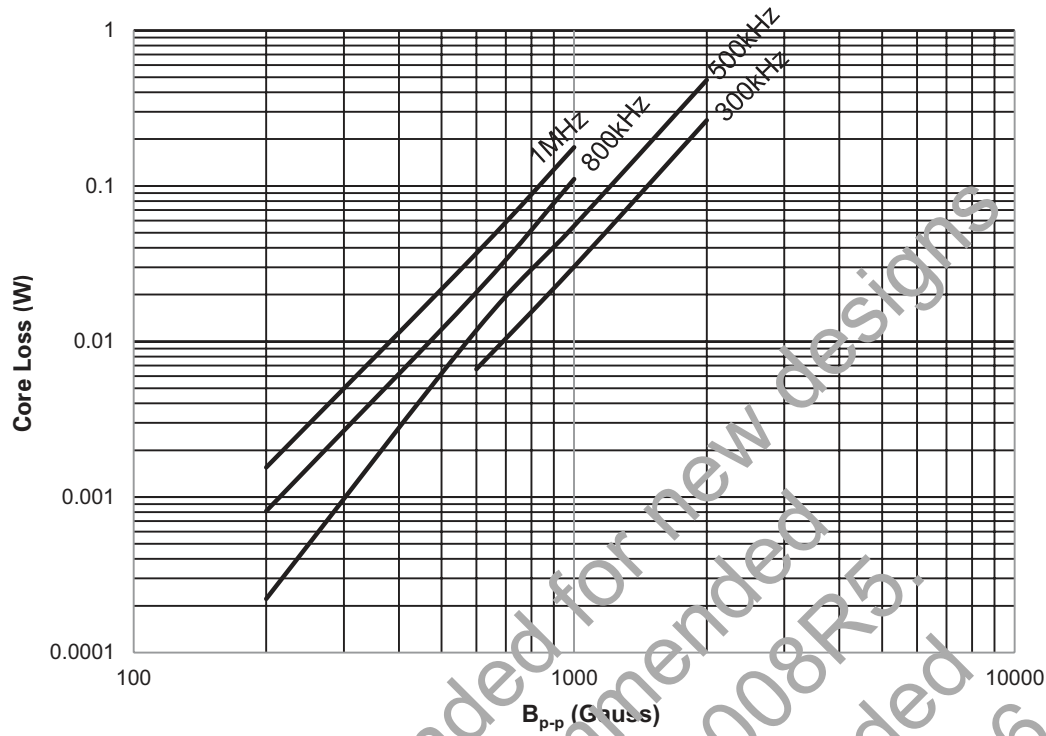
Supplied in tape and reel packaging, 500 parts per 13" diameter reel.



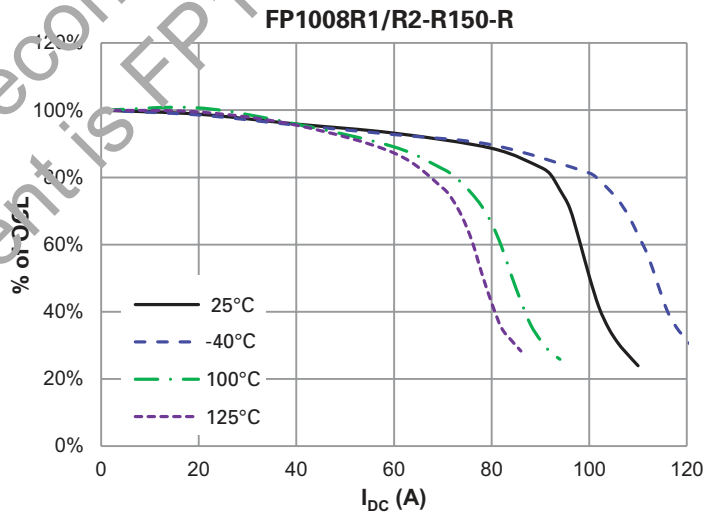
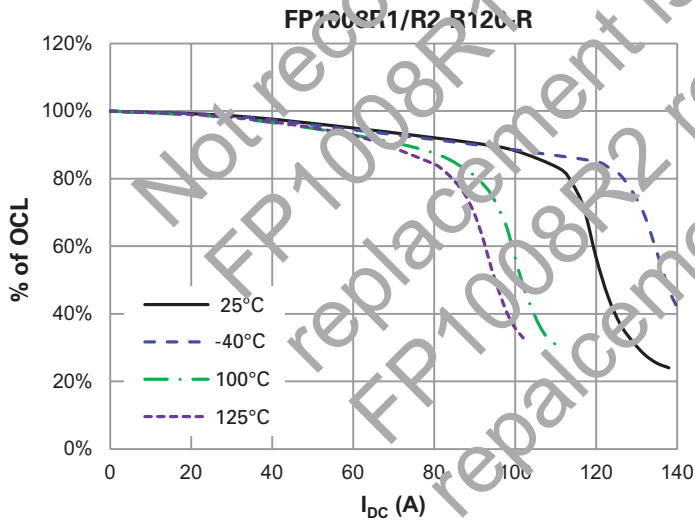
**Temperature rise vs. total loss**



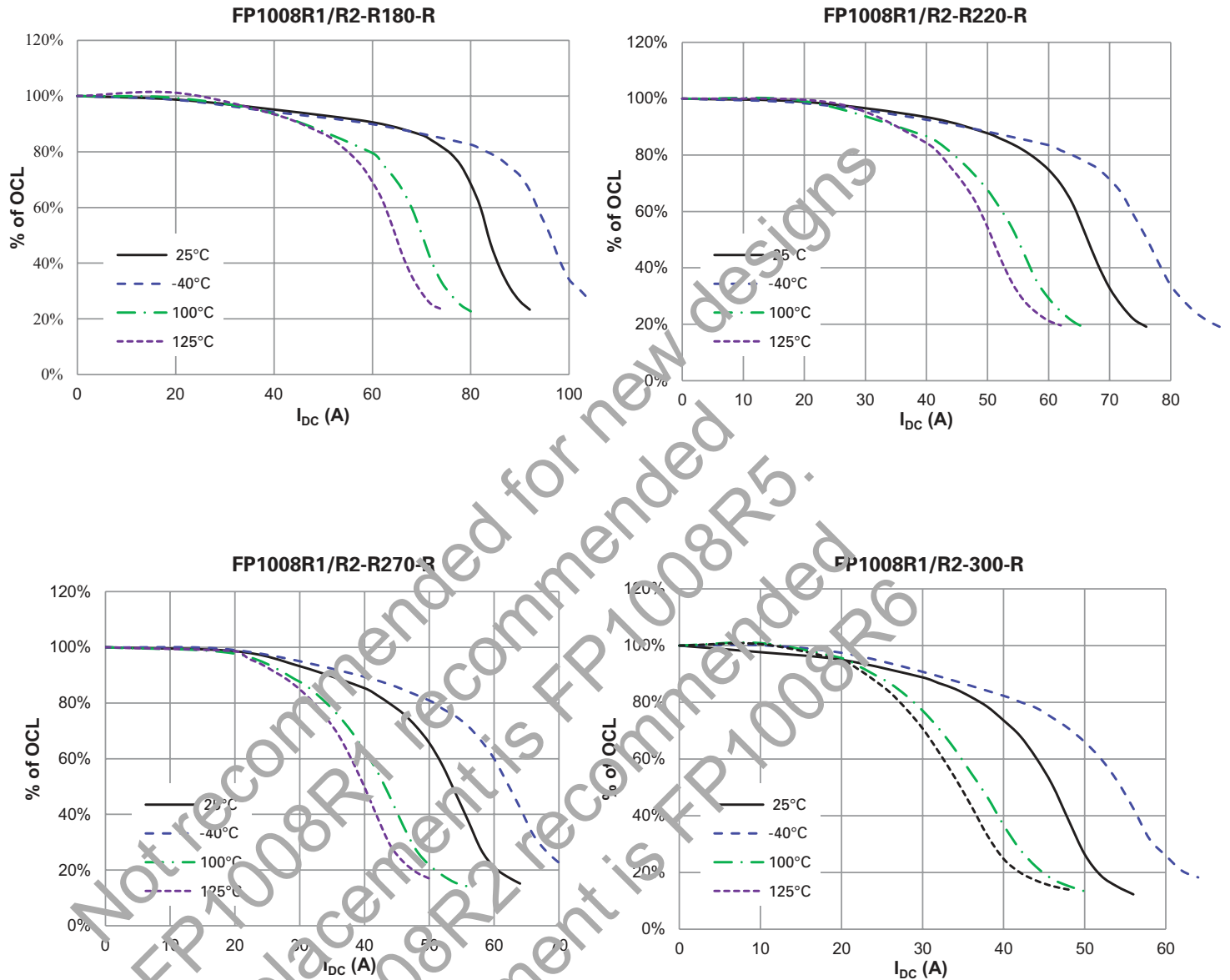
Core loss vs. Bp-p



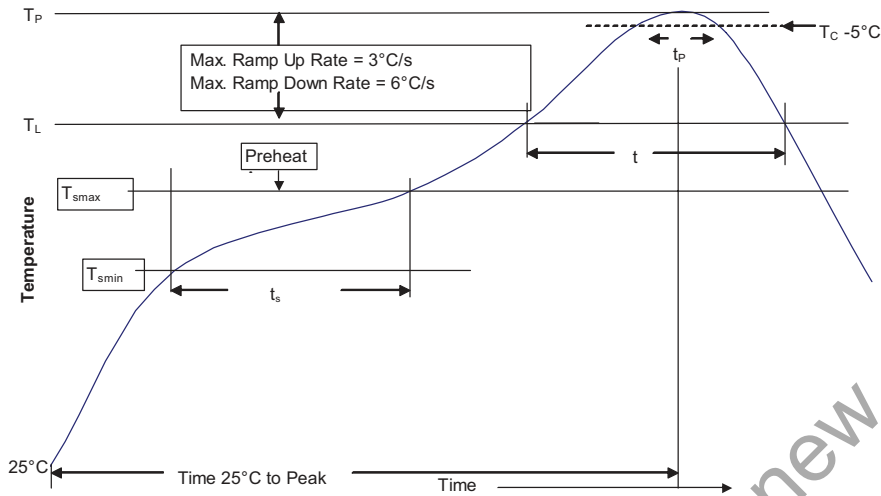
Inductance characteristics



Inductance characteristics



**Solder reflow profile**



**Table 1 - Standard SnPb Solder (T<sub>c</sub>)**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

**Table 2 - Lead (Pb) free Solder (T<sub>c</sub>)**

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

**Reference JDEC J-STD-020D**

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T <sub>smin</sub> )	100°C	150°C
• Temperature max. (T <sub>smax</sub> )	150°C	200°C
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T <sub>L</sub> )	183°C	217°C
Time at liquidous (t <sub>L</sub> )	60-150 Seconds	60-150 Seconds
Peak package body temperature (T <sub>p</sub> )*	Table 1	Table 2
Time (t <sub>p</sub> )** within 5 °C of the specified classification temperature (T <sub>c</sub> )	20 Seconds**	30 Seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

\* Tolerance for peak profile temperature (T<sub>p</sub>) is defined as a supplier minimum and a user maximum.  
\*\* Tolerance for time at peak profile temperature (t<sub>p</sub>) is defined as a supplier minimum and a user maximum.

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**Eaton**  
Electronics Division  
1000 Eaton Boulevard  
Cleveland, OH 44122  
United States  
www.eaton.com/elx

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Publication No. 10408-BU-SB15269  
June 2015

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